Devcon 5 Minute® Epoxy

Epoxy; Epoxide

Devcon

Message:

A rapid-curing, general purpose adhesive/encapsulant.
Intended Use:
Bonds metals, fabrics, ceramics, glass, wood, and concrete (in combinations)
Product features:
100% reactive, no solvents
Good solvent resistance
Bonds metals, fabrics, wood, and concrete

General Information			
Features	Solvent resistance Fast curing General		
Uses	General Bonding Adhesive		
Appearance	Amber		
Processing Method	Enclosure		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Volume	0.907	cm^3/g	
Solid content-by Volume	100	%	
Impact Resistance	11.6	kJ/m^2	
Service Temperature - Dry	-40 - 93	°C	
Work Time	3.0 - 6.0	min	
Tensile Shear Adhesion	13.1	MPa	ASTM D1002
Density [1]	1.10	g/cm^3	
Hardness	**Nominal Value**	**Unit**	**Test Method**
Durometer Hardness (Shore D)	85		ASTM D2240
Mechanical	**Nominal Value**	**Unit**	
Tensile Elongation (Break)	1.0	%	
Electrical	**Nominal Value**	**Unit**	**Test Method**
Dielectric Strength	19	kV/mm	ASTM D149
Thermoset	**Nominal Value**	**Unit**	**Test Method**
Thermoset Components			

Component a	Mixing ratio by weight: 1.0 Mixing ratio by capacity: 1.0		
Component B	Mixing ratio by weight: 1.0 Mixing ratio by capacity: 1.0		
Thermoset Mix Viscosity	10000	cP	

Additional Information	Nominal Value	Unit	Test Method
Cured 7 days @ 75°F			

Uncured Properties	Nominal Value	Unit	Test Method
Curing Time (22°C)	12	hr	

NOTE	
1.	Mixed

Recommended distributors for this material

Susheng Import & Export Trading Co.,Ltd.

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